

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

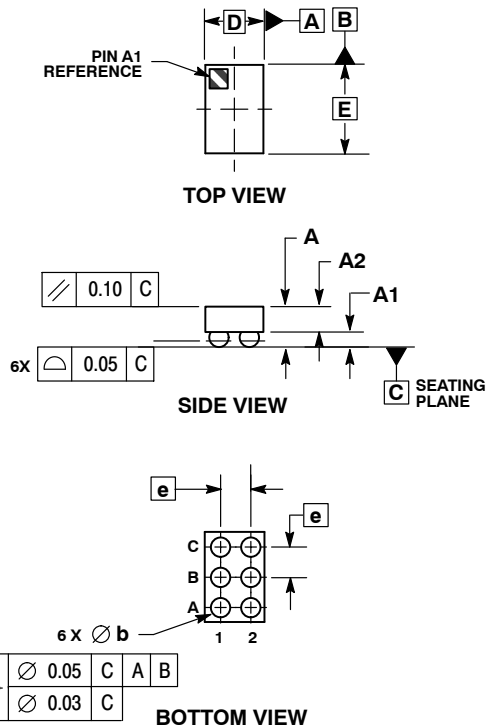
ON Semiconductor®



SCALE 4:1

6 PIN FLIP-CHIP, 1.0x1.5
CASE 499BC
ISSUE A

DATE 14 JAN 2009



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.64
A1	0.22	0.28
A2	0.34	0.36
b	0.29	0.34
D	0.92	1.00
E	1.42	1.50
e	0.50 BSC	

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DESCRIPTION: 6 PIN FLIP-CHIP, 1.0X1.5, 0.5P

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